



东沃电子
DOWOSEMI

NUP2105L

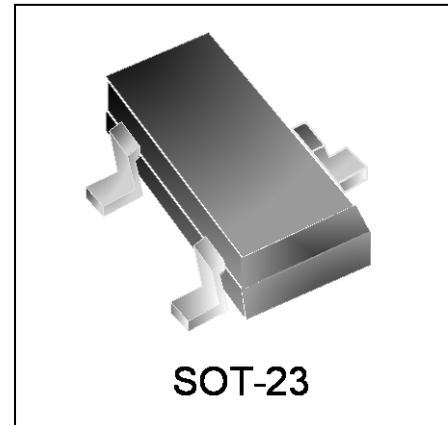
Transient Voltage Suppressor

Features

- 400 watts peak pulse power ($t_p = 8/20\mu s$)
- Response Time is Typically < 1 ns
- Protects one bidirectional line or two unidirectional lines
- Working Voltages: 24V
- Low clamping voltages

IEC COMPATIBILITY (EN61000-4)

- IEC 61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 8A (8/20 μs)



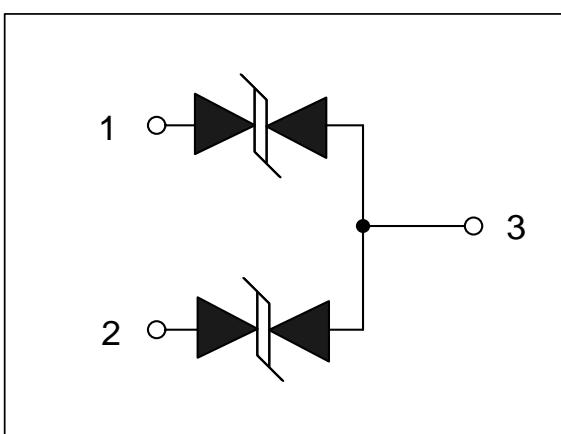
Mechanical Characteristics

- JEDEC SOT-23 package
- Molding compound flammability rating:
- UL 94V-0
- Marking : Marking Code
- Packaging : Tape and Reel per EIA 481
- RoHS Compliant

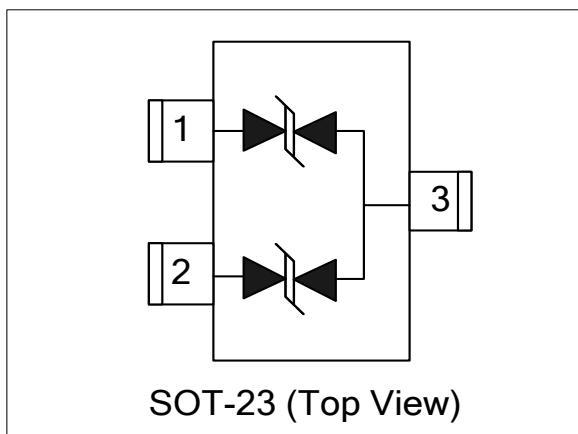
Applications

- Automotive Networks
- Control & Monitoring Systems
- Portable Electronics
- Set-Top Box
- Servers, Notebook, and Desktop PC
- Wireless Bus Protection

Circuit Diagram



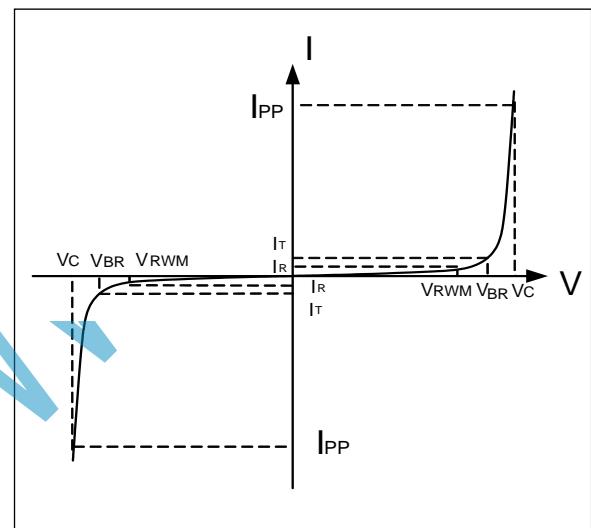
Schematic & PIN Configuration



Absolute Maximum Rating			
Rating	Symbol	Value	Units
Peak Pulse Power ($t_p=8/20\mu s$)	P_{PP}	450	Watts
Peak Pulse Current ($t_p=8/20\mu s$)	I_{PP}	8	A
Operating Temperature	T_J	-55 to + 125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Parameters (T=25°C)

Symbol	Parameter
I_{PP}	Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Reverse Stand-Off Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current



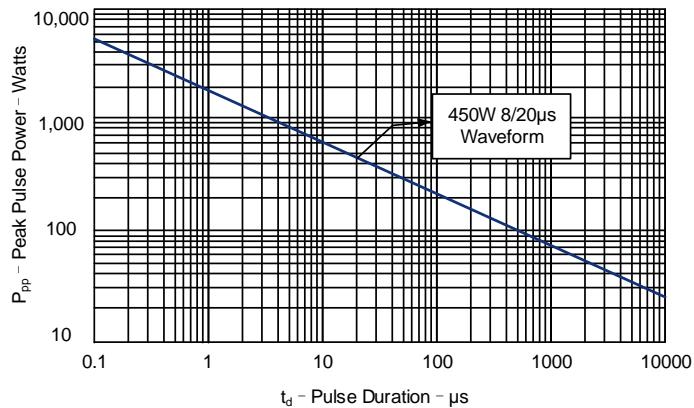
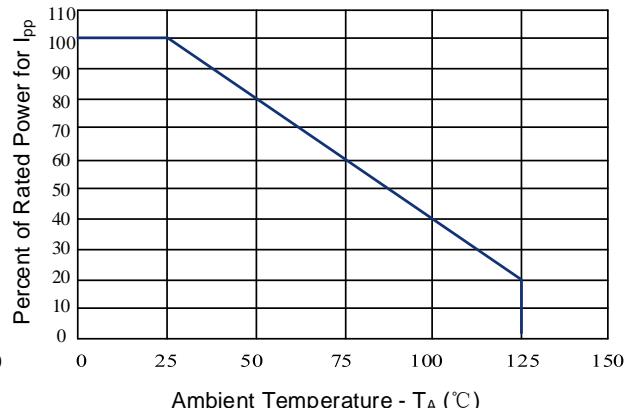
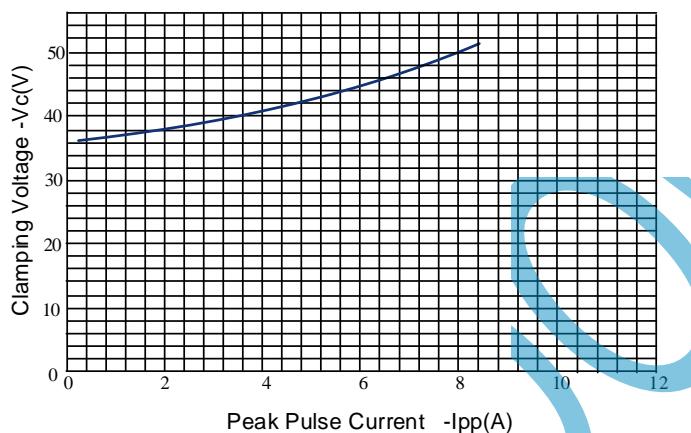
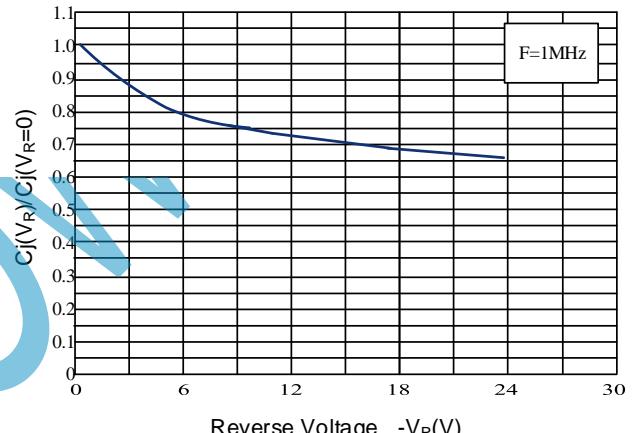
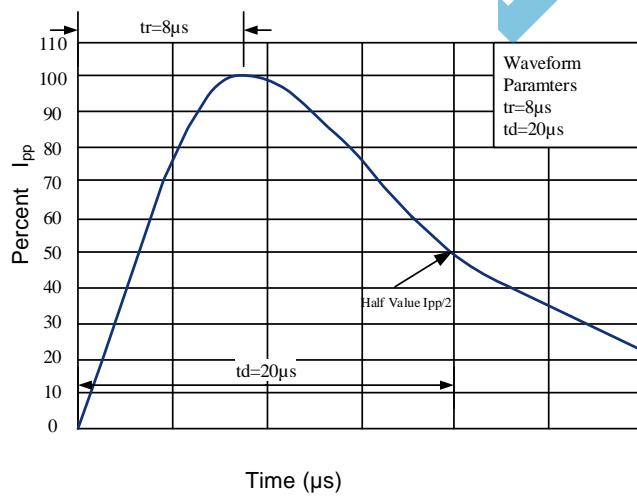
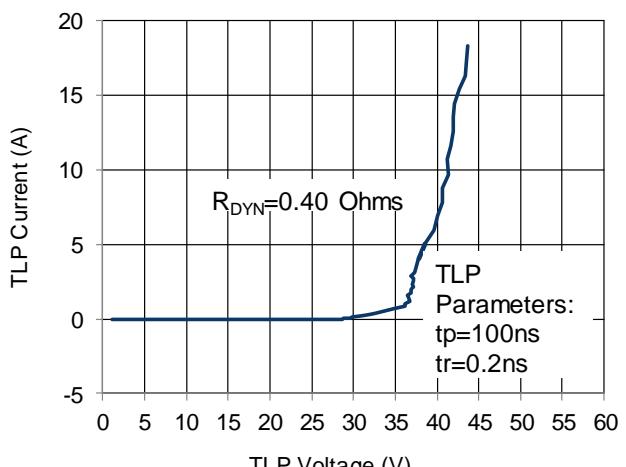
Electrical Characteristics

NUP2105L						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				24	V
Reverse Breakdown Voltage	V_{BR}	$I_T=1mA$	26..7			V
Reverse Leakage Current	I_R	$V_{RWM}=24V, T=25^\circ C$			200	nA
Clamping Voltage	V_C	$I_{PP}=8A, t_p=8/20\mu s$		50	54	V
Dynamic Resistance ^{1,2}	R_{DYN}	TLP=0.2/100ns		0.4		Ω
ESD Clamping Voltage ¹	V_C	$I_{PP} = 4A, t_p = 0.2/100ns (TLP)$		38.0		V
ESD Clamping Voltage ¹	V_C	$I_{PP} = 16A, t_p = 0.2/100ns (TLP)$		43.0		V
Junction Capacitance	C_J	Pin 1 to 3 or Pin 2 to 3 $V_R = 0V, f = 1MHz$		25	35	pF

Notes : 1. TLP Setting : $t_p=100ns, t_r=0.2ns, I_{TLP}$ and V_{TLP} sample window: $t_1=70ns$ to $t_2=90ns$.

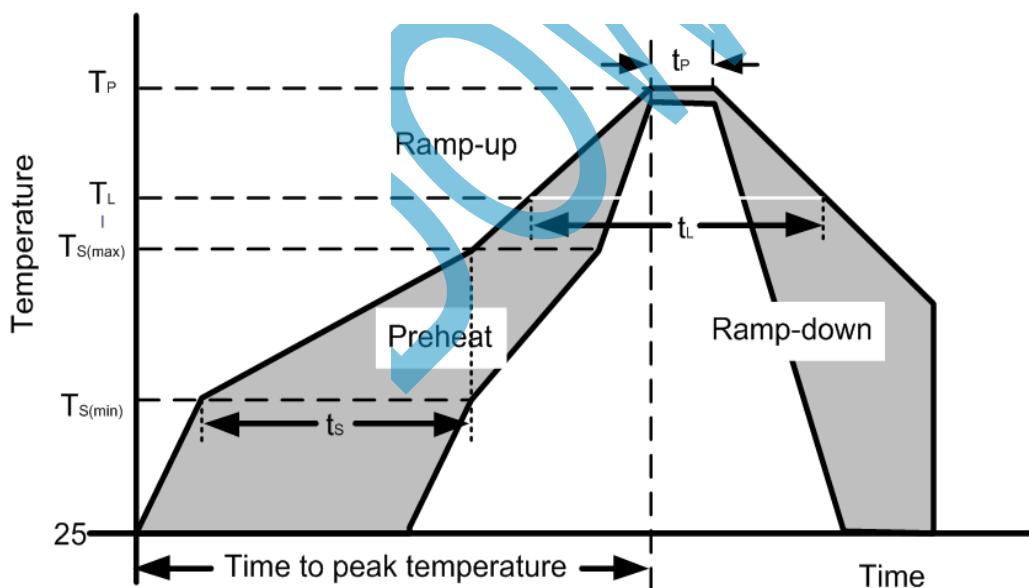
2. Dynamic resistance calculated from $I_{PP}=4A$ to $I_{PP}=16A$ using "Best Fit"

Typical Characteristics

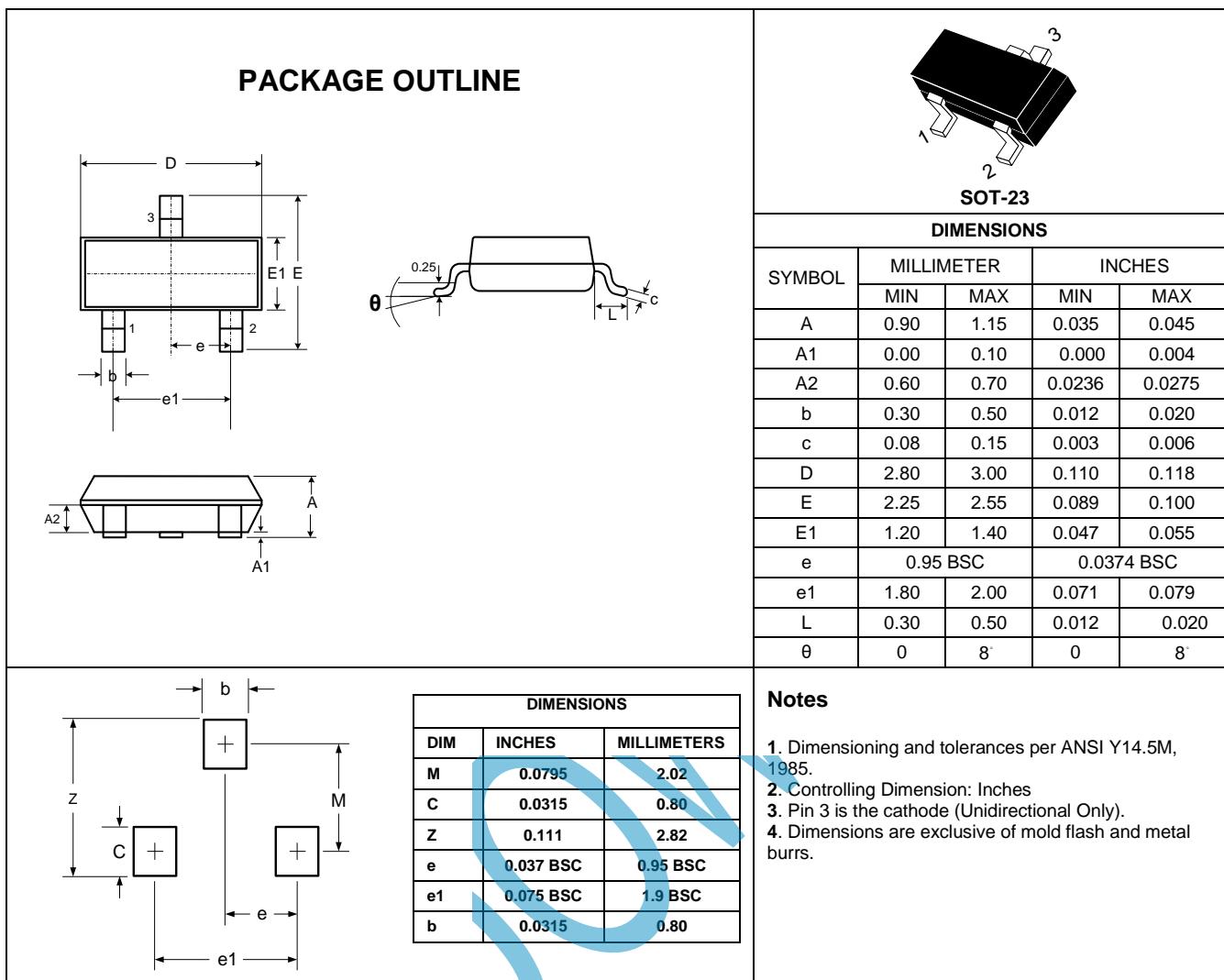
Figure 1: Peak Pulse Power vs. Pulse Time**Figure 2: Power Derating Curve****Figure 3: Clamping Voltage vs. Peak Pulse Current****Figure 4: Normalized Junction Capacitance vs. Reverse Voltage****Figure 5: 8/20 μs Pulse Waveform****Figure 6: TLP I-V Curve**

Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	Temperature Min ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 190 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
$T_{s(max)}$ to T_L — Ramp-up Rate		5°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Temperature (t_L)	60 – 150 seconds
	Peak Temperature (T_P)	260+0/-5 °C
Time within actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		280°C



Outline Drawing – SOT-23



Marking Codes

Part Number	Marking Code
NUP2105L	

Package Information

Qty: 3k/Reel